

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD90N04S4-04	**Issued**	10. May 2021
MA#	MA001610650		
Package	PG-TO252-3-313	**Weight***	319.08 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.788	0.56	0.56	5602	5602
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		462	
	non noble metal	copper	7440-50-8	147.096	46.11	46.17	461007	461607
wire	non noble metal	aluminium	7429-90-5	5.131	1.61	1.61	16080	16080
encapsulation	inorganic material	zincoxide	1314-13-2	1.387	0.43		4347	
	miscellaneous	miscellaneous	-	6.934	2.17		21733	
	plastics	epoxy resin	-	20.803	6.52		65198	
	inorganic material	silicondioxide	60676-86-0	109.563	34.34	43.46	343375	434653
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11721	11721
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4452	4463
solder	non noble metal	tin	7440-31-5	0.036	0.01		114	
	noble metal	silver	7440-22-4	0.045	0.01		142	
	non noble metal	lead	7439-92-1	1.735	0.54	0.56	5437	5693
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.01	6.02	60103	60181
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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